

4C3 Crib

i) A pyroelectric element produces charge in response to a change in temperature. However for a small change in T this dissipates and is difficult, if not impossible, to measure. An incident modulated flux of heat energy gives rise to a ac current and voltage which can be amplified. $i_p = A\rho \frac{dT}{dt}$

ii) In this case the multiple Fresnel lenses create a large number of areas which are focussed onto the detector. A warm body moving through the detection zones creates, therefore a time modulated incident flux on the detector. $W(t) = W_0 e^{i\omega t}$ ω here depends on the rate at which the object cuts across the detection zones.

iii) There are two basic approaches - The current / voltage responsivity is proportional

to ω . So if the intruder moves very slowly it is possible that the signal produced is below the detection threshold of the detector. The other approach would be to reduce the magnitude of the incident flux. Wearing low-emissivity clothing or insulation so the intruder was at the same T as the surroundings would also reduce the signal.

Finally you could shine a bright IR source at one detector and overload it. This might cause an initial detection though.

iv) A cold object is just as likely to trigger as a hot object as the detector is sensitive to $\frac{dT}{dt}$

b) i) $R_V = \frac{V}{W_0}$ here $V = \frac{i_p}{Y_c}$
↙
amplifier's
complex admittance

reciprocal of impedance

$$\text{so } R_v = \frac{i\rho}{Y W_0}$$

ii) From $Y = \frac{1}{R_0} + i\omega C$ ($C = C_E + C_A$)

We also know that $G_T \tilde{Y}_T = H$

Simple eqn
expected
(to remember
or derive)

$$\tilde{Z}_E = \frac{C}{R_0} \frac{dT}{dt}$$

$$\left(i\rho = A_p \frac{dT}{dt} \right) = A_p \left(\frac{i\omega \eta W_0 e^{i\omega t}}{G_T + i\omega H} \right)$$

$$\text{so } R_v = \frac{i\rho}{Y W_0} = \frac{A_p \eta W_0 e^{i\omega t} i\omega}{\left(\frac{1}{R_0} + i\omega C \right) G_T (H + i\omega \tilde{Z}_T)}$$

from $\tilde{Z}_T = \frac{H}{G_T}$

$$C = \tilde{Z}_E / R_0 = \frac{R_0 A_p \eta e^{i\omega t} i\omega}{(1 + i\omega \tilde{Z}_E)(1 + i\omega \tilde{Z}_T)}$$

rest

$$R_v = \frac{R_o A_p \eta e^{i\omega t} i\omega (1+i\omega Y_G)(1-i\omega Y_T)}{G_T (1+\omega^2 Y_T^2) (1+\omega^2 Y_G^2)}$$

$$|R_v|^2 = R_v R_v^* = \frac{R_o^2 A_p^2 \eta^2 \omega^2 (\cancel{1+i\omega Y_G^2})(\cancel{1-i\omega Y_T^2})}{G_T^2 (1+\omega^2 Y_T^2) (1+\omega^2 Y_G^2)}$$


so $|R_v| = \frac{R_o A_p \eta \omega}{G_T \sqrt{1+\omega^2 Y_T^2} \sqrt{1+\omega^2 Y_G^2}}$

iii) If ω is large

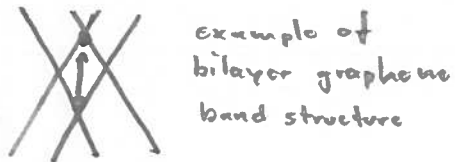
$$\frac{R_o A_p \eta}{G_T \omega^2 Y_T Y_G}$$

so at large ω $R_v \propto 1/f$

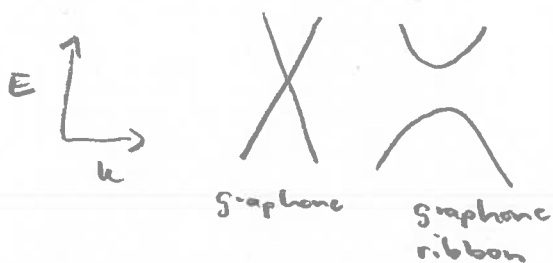
Q2 a) Monolayer NbS_2 is metallic, as Fermi level is mid-band, i.e. there is partially filled band. Question was seeking careful consideration, so if rightly argued (not taking $E_F = 0\text{eV}$) also full points awarded to semiconductor argumentation.

b) i)  Band dispersion is linear for graphene, and graphene is semi-metal or zero-gap semiconductor.

ii) The visibility of monolayer graphene on SiO_2/Si support comes from interference effects. The different colour for different twist angles of bilayer graphene is associated with enhanced absorption based on transitions to states that arise from different band overlaps (see figure).



iii) For ribbons with small enough width confinement effects will occur, alike to carbon nanotubes. This results in the original 2D energy dispersion to split into 1D modes (CNTs). If these 1D modes do not pass through intersection of conduction and valence band (k point), then these ribbons have finite gap.



widths below 20 nm can give band gaps $> 200\text{meV}$, for well controlled very small widths gaps $> 1\text{eV}$; a comparison again to CNTs here is helpful as order of magnitudes are similar.

The mobility will decrease with ribbon width, however, which is similar to conventional semiconductors.

mobility
[cm^2/Vs]



Q2 c) i) Transparent conducting layer could be designed using graphene. The optical transmittance is $\sim 2.3\%$ per layer, and it will also be transparent in UV due to its thinness. High conductivity requires high mobility and high carrier concentration. So ideally highly crystalline graphene film and effective doping. Best solution to use few-layer graphene. Carbon nanotubes would offer similar design solution, but LED emitter integration will not be as easy (see ii).

ii) UV-C range is $\sim 200-300$ nm wavelength, so large band gap (> 4 eV) emitter material is required for LED. A solution is AlGaN, as highlighted in the lectures by "Map of the world" material diagram. AlN and GaN have sim. lattice constant so heterostructure for efficient LED design can be fabricated. To relax epitaxy constraint, material ^{stack} can be grown as vertical nanowire. Graphene (see i) is 2D material, so epitaxial constraint is relaxed, and AlGaN material of sufficient quality can be grown directly on it. Alternatively, a transfer solution can be discussed for device assembly.

Q3 a) i) As is group V, so substitutional n-type doping of Ge will occur.

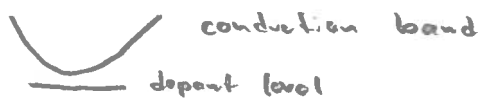
ii) hydrogenic model

$$E_{\text{donor}} = -R_0 \frac{m^*}{\epsilon_r^2} \quad \text{for ground state below Ge conduction band}$$

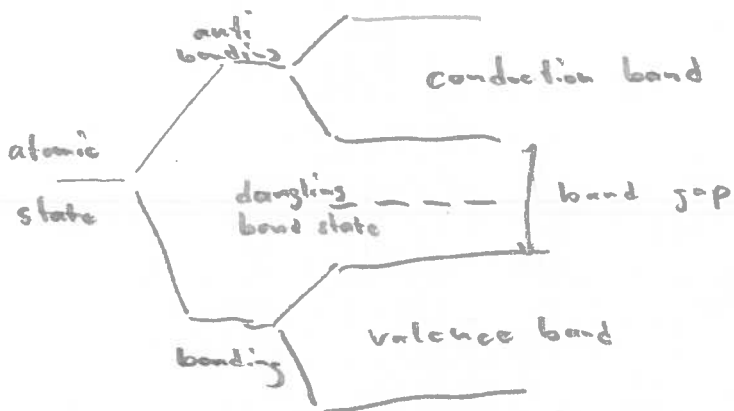
$$= -13.6 \text{ eV} \frac{0.55}{16^2} = 29 \text{ meV}$$

use effective mass for electrons as its n-type doping.

This is of order of kT at 300K, so donor level will be ionised.



iii) vacancy will have dangling bond and, using covalent bonding / antibonding picture, this will lead to state in mid-gap:



Such defects act like a "free radical" and can act as trapping and recombination centre, i.e. are electronically detrimental.

iv) CMOS technology is based on MOSFET transistors where not only semiconductor but also good dielectric is required. Electronic properties of SiO_2 are good, it is stable and importantly SiO_2 formation passivates dangling bonds of Si at interface. So low interface defect density

Q3 a) iv) can be achieved. Ge does not have such a stable and useful native oxide. Hence Si became the dominating material.

b) Ge has indirect band gap of ~ 0.7 eV.

The Shockley - Queisser limit places maximum solar conversion efficiency around 33.7% for single p-n junction with a material of 1.4 eV.

This means Ge band gap is too small. Si is better but still indirect band gap. Higher efficiency possible with direct band gap material like GaAs or hybrid perovskite like $\text{CH}_3\text{NH}_3\text{PbI}_3$.

c) i) Band diagram shows linear dispersion around K-point, with conduction and valence band touching. So its analogous to graphene, and germanene is semi-metal or zero band gap semiconductor. So not good material for standard transistor, but it is 2D Dirac material with anomalous quantum effects with potential for novel optoelectronic devices.

ii) Si and Ge are analogous here in this traditional semiconductor vs new 2D phase comparison. Silicene will also have linear dispersion and zero gap:



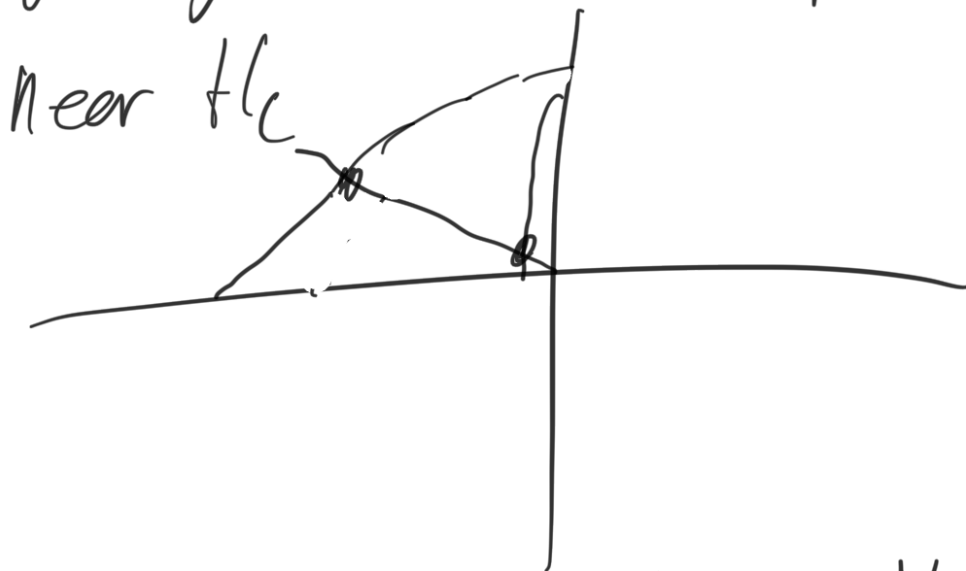
4(3) Crib 3

4 a) i) For $h = r$ $N \approx \frac{1}{2}$

(students expected to recall)

Coalt-Steel has a low μ lowest of all "permanent" magnet materials.

De-mag effect will cause spontaneous demagnetisation as operating point



SmCo has much larger $H_c > 600 \text{ kA m}^{-1}$
vs ~ -20 will stay magnetised even

with $N = \dots$

ii) So

$$B = \mu_0(H + M)$$

$$H = -MN \quad M = -\frac{H}{N}$$

$$B = \mu_0\left(-\frac{H}{N} + H\right)$$

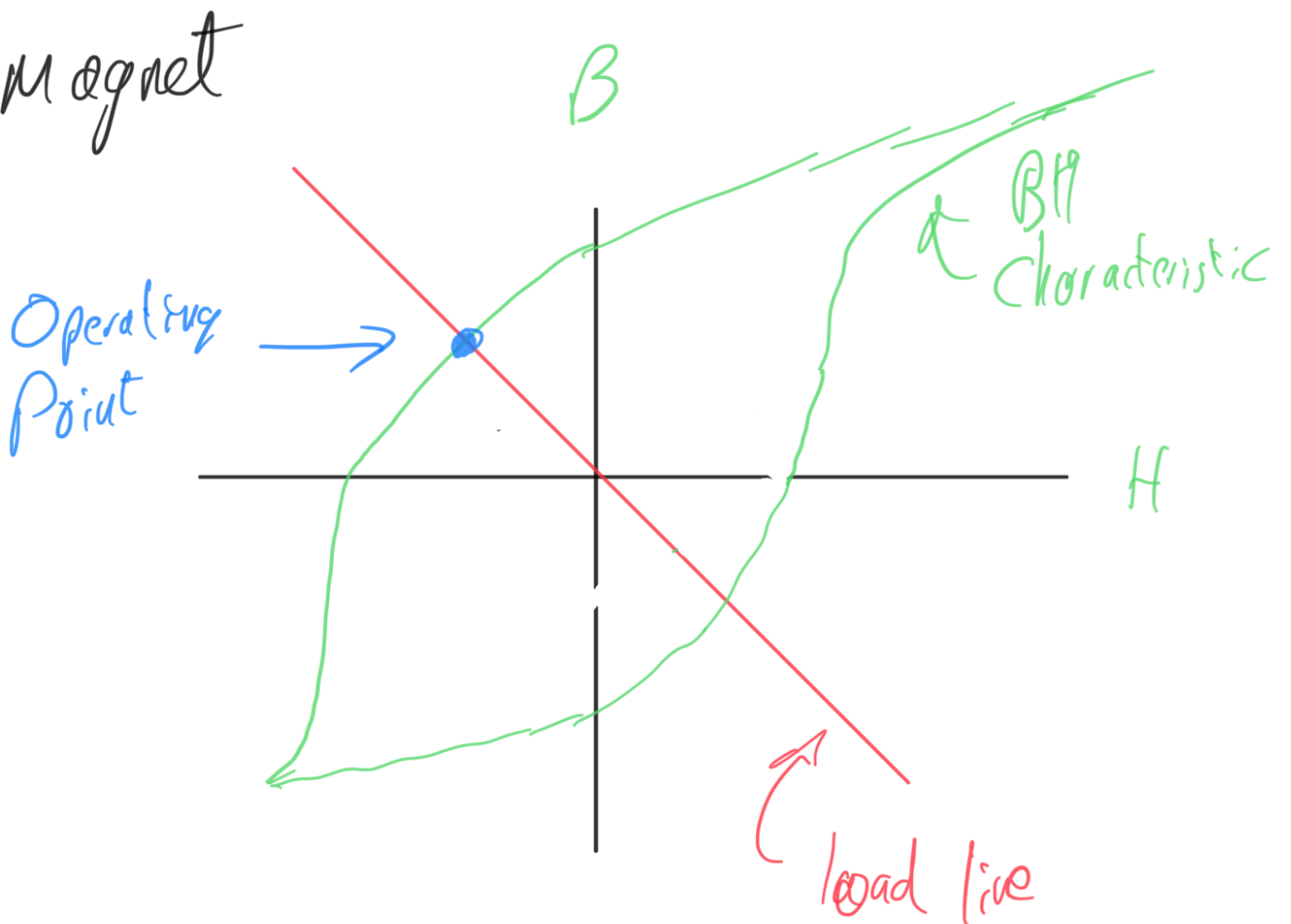
$$B = H \mu_0 \left(1 - \frac{1}{N}\right)$$

$$\frac{B}{H} = \mu_0 \left(1 - \frac{1}{N}\right) = -\mu_0 \left(\frac{1-N}{N}\right)$$

must be satisfied for a given N

iii) C is the B-H characteristic

set by material's properties and
 $\frac{B}{H} = -\mu_0 \left(\frac{1-N}{N} \right)$ set by values of
 N - the intersection of these
 is the "operating" point of the
 magnet



iv)

14/

$$B = \mu_0 (M + H)$$

but $H = -MN$ ^{density}
 \propto to energy in field actually $\frac{BH}{2}$

$$\mu \frac{BH}{\mu_0} = -MN(M - MN)$$

$$= -M^2 N(1 - N)$$

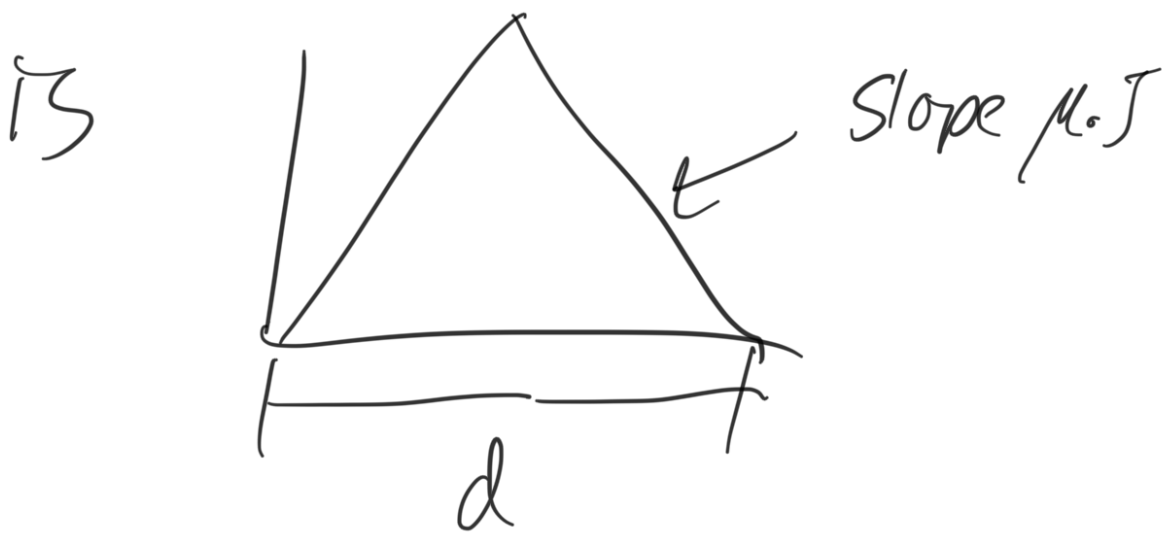
$$\text{so } BH = (M^2 N^2 - M^2 N) \mu_0 = \mu_0 M^2 (N^2 - N)$$

max when $\frac{d(BH)}{dN} = 0$

$$\frac{d(BH)}{dN} = \mu_0 (2N - 1) = 0$$

i.e. when $N = \frac{1}{2}$

b) i) For superconductor field profile



Peak field is $\mu_0 J \frac{d}{2}$

$$1.257 \times 10^{-6} \times 1 \times 10^8 \times 3 \times 10^{-3}$$

$$= 0.3771 \text{ T}$$

but M is half this (as need to

Integrate in this simple case /

$$\text{so } \mu_0 M = 0.18855 \text{ T}$$

$$M = 1.5 \times 10^5 \text{ A/m}$$

For $N \neq 4\pi$. $N = 0$ or

Operating point is $H = 0$ as $-MN = 0$

$B = \mu_0 M$ From data book

$$B = 2.32 \text{ T}$$

as magnet M is same everywhere

$$M = 2 \times 10^6 \text{ A/m}$$

ii) So... if (the critical current of a superconductor is not that high

Small pieces of superconductor would still be inferior to permanent magnet materials.

However as made for a superconductor. (this would not hold for larger samples)

Also T_c is 30°C - very easy to demagnetise.